

Application No. 09/830253  
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*Marked-Up Text*

*Version with markings to show changes made*

**In The Claims:**

*Please amend the claims as follows:*

1) (Amended twice) Method for producing an electronic module in the shape of a ball housing combining a network of balls (7) or geometrically identical preform connectors or shield system and surface-mounted components (2) on the same side of a substrate (1), thus making this module directly connectable [by soldering] to a printed circuit (3), wherein

soldering cream (8) is deposited simultaneously for the components and the connecting ball or shield system located on the same surface;

said components are transferred onto the corresponding mounting lands;

the ball connectors [with a diameter greater than the height of said components] are transferred collectively onto the lands of the same side intended for them by an appropriate device; and

a single re-melting cycle permits simultaneous soldering of the components and the connecting balls or shields onto the substrate.

*Please add the following claims:*

10. (New) Method as claimed in claim 1, the module being directly connectable by soldering to the printed circuit.

11. (New) Method as claimed in claim 1, wherein the ball connectors have a diameter greater than the height of said components.